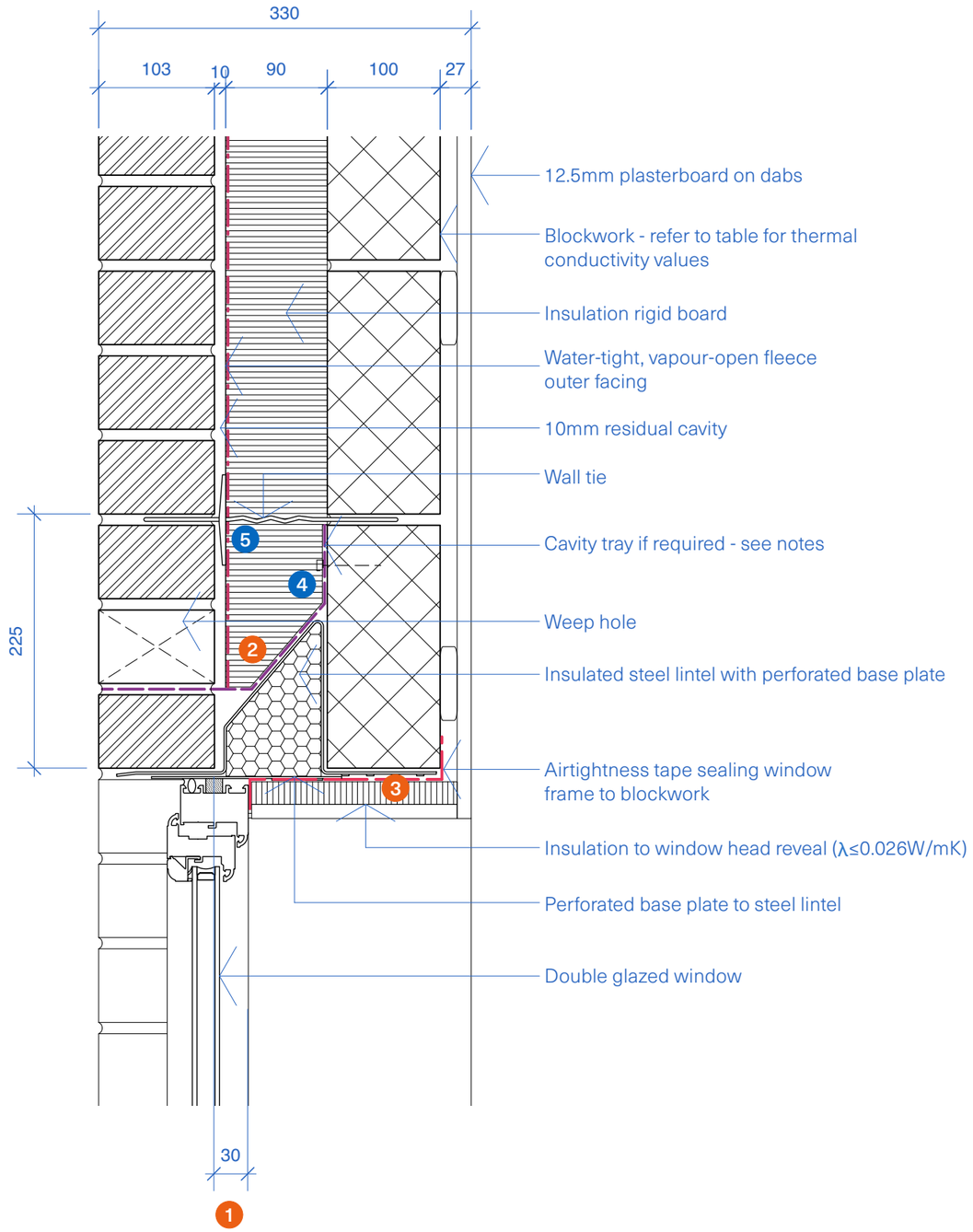
Construction Detail



Calculated Ψ (Psi) value for use in SAP Calculation

	Internal leaf block thermal conductivity (W/mK)					
Insulation thermal conductivity (W/mK)	0.11	0.15	0.19	0.28	0.6	1.33
0.019	**0.251**	**0.275**	**0.295**	**0.328**	**0.390**	**0.446**
0.022	**0.244**	**0.268**	**0.288**	**0.320**	**0.381**	**0.436**

f-values: 0.844 - 0.916 (values above 0.75 indicate low risk of condensation and mould)

Ψ (Psi) value Thermal Compliance Notes

1. Minimum 30mm overlap of window frame and insulated wall cavity.
2. Ensure insulation rigid board is cut and fitted above the angle of the cavity tray.
3. 20mm insulation with λ≤0.026W/mK to head reveal.

Construction Notes

4. If using galvanised lintel cavity tray is required.
   Secure the cavity tray DPC to the face of the blockwork using a compatible double-sided adhesive tape. Do not create a slip plane by continuing the DPC into the same mortar joint as the wall tie.

5. Wall tie: 225mm maximum distance from opening. No greater than 450mm vertical spacing.
   450mm horizontal centres for first row of wall ties above and below opening.
   Only use insulation retaining clips that are compatible with the wall tie.

General Notes

The cavity must be closed at the top of the wall and openings for the provisions of Diagram 5.3 ADBv1 to apply.